TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (π -MOS VI)

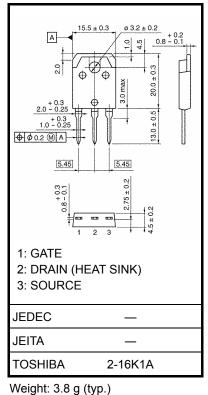
TK20H50C

Switching Regulator Applications

- Low drain-source ON resistance $: RDS (ON) = 0.23\Omega (typ.)$
- High forward transfer admittance $|Y_{fs}| = 14 \text{ S (typ.)}$
- Low leakage current $: I_{DSS} = 100 \ \mu A \ (max) \ (V_{DS} = 500 \ V)$
- Enhancement mode : $V_{th} = 2.0 \sim 4.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ ID} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit
Drain-source voltage		V _{DSS}	500	V
Drain-gate voltage (R	_{GS} = 20 kΩ)	V _{DGR}	500	V
Gate-source voltage		V _{GSS}	±30	V
Drain current	DC (Note 1)	I _D	20	А
	Pulse (Note 1)	I _{DP}	80	А
Drain power dissipation	n (Tc = 25°C)	PD	150	W
Single-pulse avalanche	e energy (Note 2)	E _{AS}	960	mJ
Avalanche current		I _{AR}	20	А
Repetitive avalanche e	nergy (Note 3)	E _{AR}	15	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature range		T _{stg}	-55~150	°C



Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Thermal Characteristics

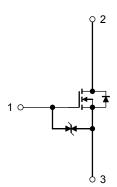
Characteristic	Symbol	Мах	Unit
Thermal resistance, channel to case	R _{th (ch−c)}	0.833	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	50	°C / W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V_{DD} = 90 V, T_{ch} = 25°C (initial), L = 4.08 mH, R_G = 25 Ω , I_{AR} = 20 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



Unit: mm

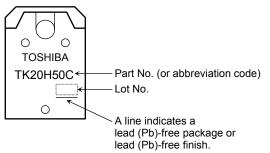
Electrical Characteristics (Ta = 25°C)

Chara	cteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	ırrent	I _{GSS}	V_{GS} = ±25 V, V_{DS} = 0 V	_		±10	μA
Gate-source bro	eakdown voltage	V _(BR) GSS	I _G = ±10 μA, V _{DS} = 0 V	±30	_	_	V
Drain cutoff curr	ent	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V	_	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	500	-	_	V
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	-	4.0	V
Drain-source O	N resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 10 A	-	0.23	0.27	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 10 V, I _D = 10 A	7.0	14	_	S
Input capacitance	ce	C _{iss}		-	3100	_	
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	20	_	pF
Output capacitance		C _{oss}		-	270	_	
Switching time	Rise time	tr	$V_{GS} \stackrel{10 V}{_{0 V}} \int_{U_{DD}} \stackrel{I_{D} = 10A}{_{0 U_{DD}}} R_{L} = 20 \Omega$ VDD $\approx 200 V$ Duty $\leq 1\%$, t _w = 10 μs	_	70	_	
	Turn on time	t _{on}		_	130	_	
	Fall time	t _f		_	70	_	ns
	Turn off time	t _{off}		_	280	_	
Total gate charge (gate-source plus gate-drain)		Qg			62	_	
Gate-source charge		Q _{gs}	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 20 A	—	40	—	nC
Gate-drain ("Miller") charge		Q _{gd}]		22	—	

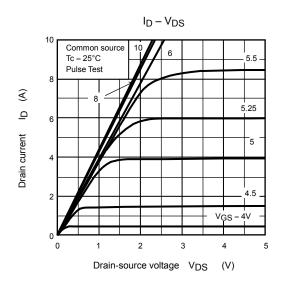
Source–Drain Ratings and Characteristics (Ta = 25°C)

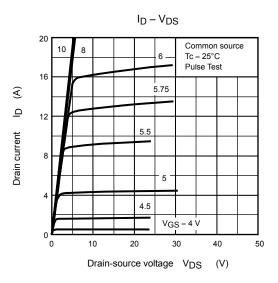
Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	20	А
Pulse drain reverse current (Note 1)	I _{DRP}	—	_	_	80	А
Forward voltage (diode)	V _{DSF}	I _{DR} = 20 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 20 A, V _{GS} = 0 V	_	1200		ns
Reverse recovery charge	Q _{rr}	dI _{DR} / dt = 100 A / µs	_	18	_	μC

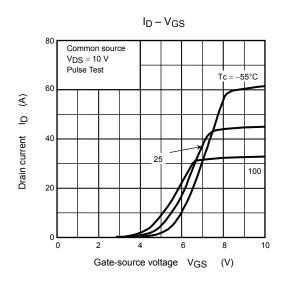
Marking

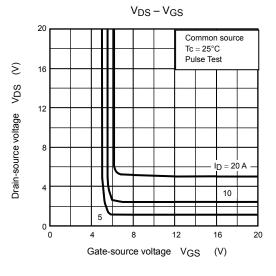


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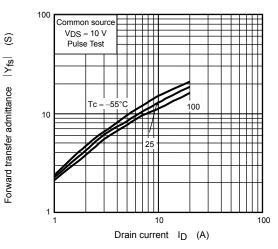




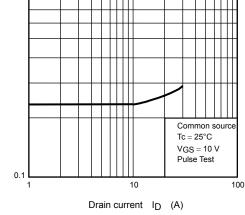












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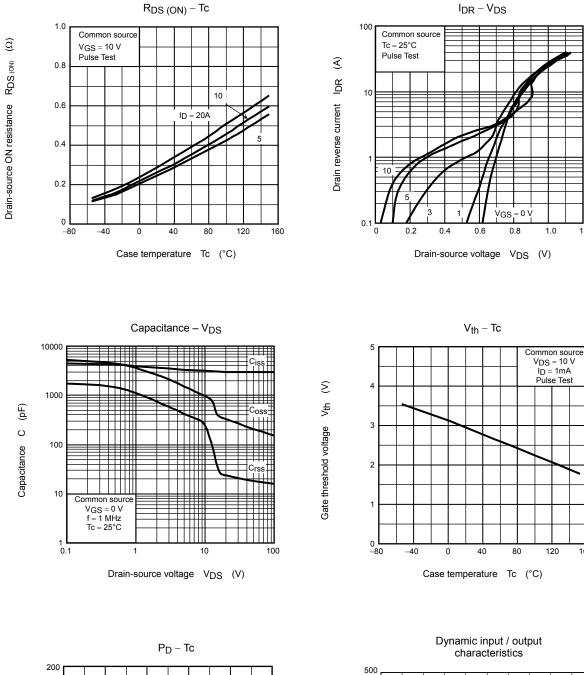
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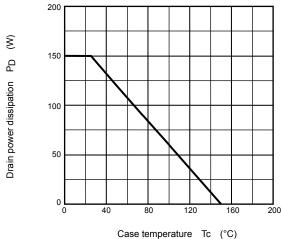
Drain-source ON resistance RDS (ON)

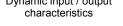
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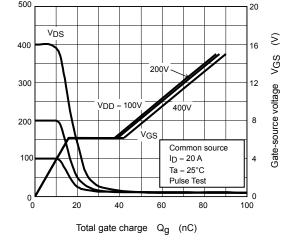
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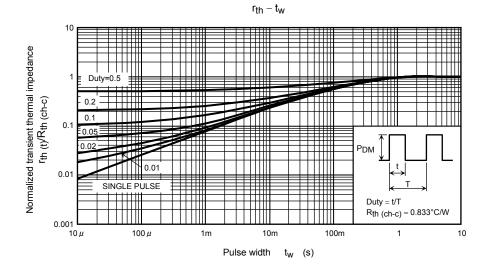




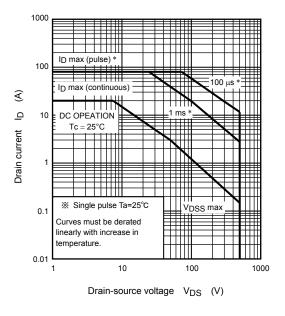
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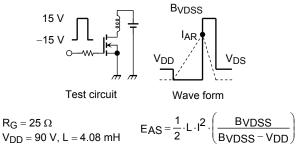
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Drain-source voltage VDS



SAFE OPERATING AREA





 $E_{AS} - T_{ch}$

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